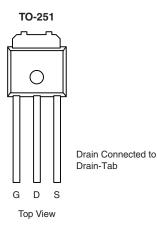


RoHS

COMPLIANT

## N-Channel 200V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω)	I <sub>D</sub> (A)		
200	0.056 at V <sub>GS</sub> = 10 V	25		
200	0.070 at V <sub>GS</sub> = 6 V	23		

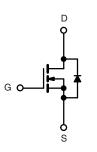


#### FEATURES

- TrenchFET<sup>®</sup> Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

• Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V <sub>DS</sub>	200	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20	v			
Constitutions Desire Connect (T 175 %C)	T <sub>C</sub> = 25 °C	1-	25			
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	17			
Pulsed Drain Current	I <sub>DM</sub>	60	A			
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	19				
Avalanche Current	I <sub>AS</sub>	25				
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	18	mJ		
Maximum Power Dissingtion	T <sub>C</sub> = 25 °C	P <sub>D</sub>	145 <sup>b</sup>	w		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3.5 <sup>a</sup>	V		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
hunsting to Ampliant	t ≤ 10 s	R <sub>thJA</sub>	15	18		
Junction-to-Ambient <sup>a</sup>	Steady State		40	50	°C/W	
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.85	1.1		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. See SOA curve for voltage derating.

Parameter     Static     Drain-Source Breakdown Voltage     Gate Threshold Voltage     Gate-Body Leakage	Symbol   V <sub>DS</sub> V <sub>GS(th)</sub>	Test Conditions $V_{GS} = 0 \text{ V}, \text{ I}_D = 250 \mu\text{A}$	Min.	Typ. <sup>a</sup>	Max.	Unit	
Gate Threshold Voltage	V <sub>GS(th)</sub>	00 B .	000				
			200				
Gate-Body Leakage		$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	2		4	V	
	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$ $V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			50		
				250			
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	40			Α	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$	0.056 0.130			_	
	Б	$V_{GS}$ = 10 V, I <sub>D</sub> = 5 A, T <sub>J</sub> = 125 °C					
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}, \text{ T}_{J} = 175 ^{\circ}\text{C}$		0.260	Ω		
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 5 A	0.070				
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 19 A		35		S	
Dynamic <sup>a</sup>		· · · · · · · · · · · · · · · · · · ·					
Input Capacitance	C <sub>iss</sub>			2400		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, F = 1 MHz		280			
Reverse Transfer Capacitance	C <sub>rss</sub>			180			
Total Gate Charge <sup>c</sup>	Qg			40			
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 100 V, $V_{GS}$ = 10 V, $I_{D}$ = 19 A		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			15		]	
Gate Resistance	R <sub>g</sub>		0.5		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 100 V, $R_L$ = 5.2 $\Omega$		50	75	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\rm I_D \cong 19$ A, $\rm V_{GEN}$ = 10 V, $\rm R_g$ = 2.5 $\Omega$		30	45		
Fall Time <sup>c</sup>	t <sub>f</sub>			60	90		
Source-Drain Diode Ratings and Cha	racteristics (1	Γ <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				50	A	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 19 A, V <sub>GS</sub> = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 19 A, dl/dt = 100 A/μs		180	250	ns	

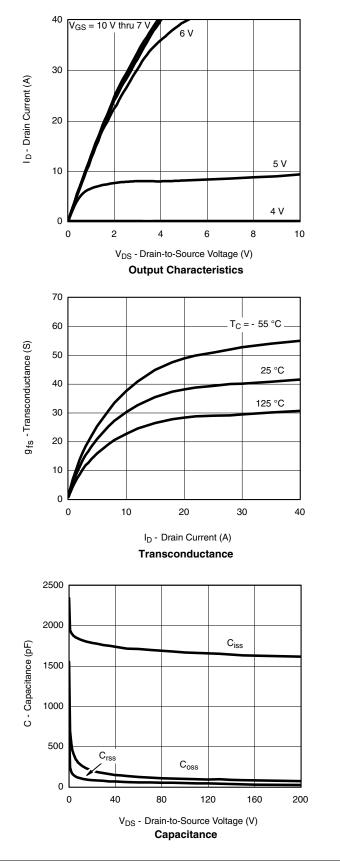
Notes: a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. c. Independent of operating temperature.

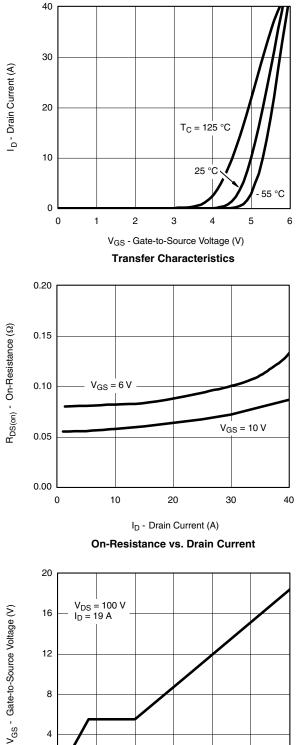
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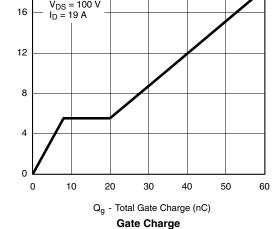
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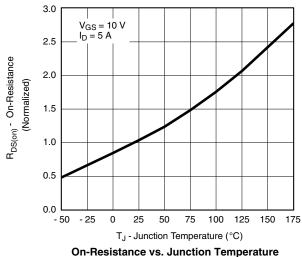


T<sub>J</sub> = 25 °C

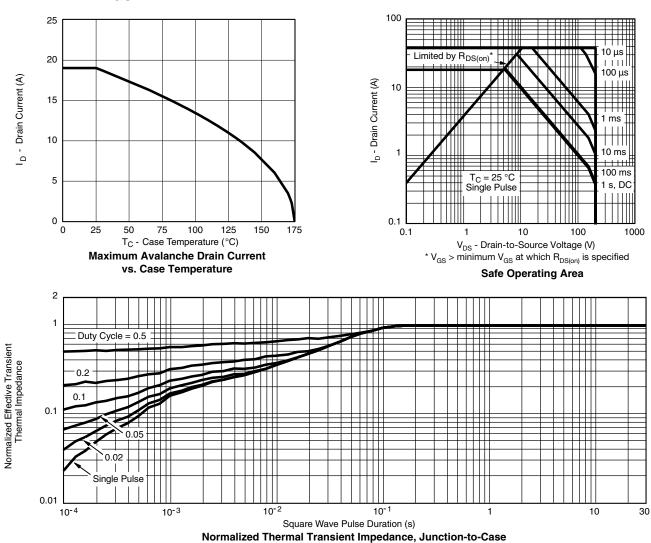
0.9

1.2









100

10

1

0

0.3

T<sub>J</sub> = 150 °C

0.6

Source-Drain Diode Forward Voltage

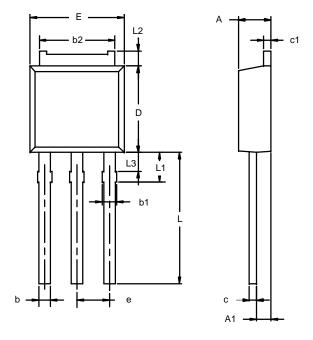
V<sub>SD</sub> - Source-to-Drain Voltage (V)

I<sub>S</sub> - Source Current (A)

### IRFU24N15DPBF



#### **TO-251AA**



	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

Note: Dimension L3 is for reference only.



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